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N-Channel 100 V (D-S) Super Junction MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}$ (m Ω) (Typ.)	I _D (A) ^a	Q _g (Typ.)			
100	6 at V _{GS} = 10 V	EE	27 nC			
100	10.5 at V _{GS} = 4.5 V	55				

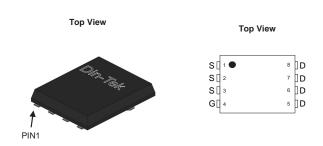
FEATURES

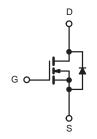
- DT-SJ Power MOSFET
- 100 % Rg and UIS tested
- Low on-resistance RDS(on)

APPLICATIONS

- DC/DC Primary Side Switch
- Telecom/Server 48 V, Full/Half-Bridge DC/DC

DFN5X6-8L Pin Configuration





N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)					
PARAMETER	SYMBOL	LIMIT	UNIT		
Drain-Source Voltage	V _{DS}	100	V		
Gate-Source Voltage	V _{GS}	± 20			
Continuous Proin Correct /T 450 90\2	T _C = 25 °C		55	А	
Continuous Drain Current (T _J = 150 °C) ^a	T _C = 100 °C	- I _D	33		
Pulsed Drain Current ^b	I _{DM}	200			
Single Avalanche Energy	E _{AS}	355	mJ		
Maximum Power Dissipation ^c	T _C = 25 °C	P _D	108	W	
Maximum Fower Dissipation	T _C = 100 °C	- FD	62		
Operating Junction and Storage Temperature Rar	T _J , T _{stg}	-55 to +150	°C		

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	LIMIT	UNIT		
Junction-to-Ambient (PCB Mount) ^d	R _{thJA}	45	°C/W		
Junction-to-Case (Drain)	R _{thJC}	1.15	1 °C/VV		

Notes

- a. Calculated continuous current based on maximum allowable junction temperature.
- b. Repetitive rating; pulse width limited by max. junction temperature.
- c. Pd is based on max. junction temperature, using junction-case thermal resistance.
- d. The value of Reja is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with Ta=25 °C.

Parameter	Symbol	Test Conditions Min.		Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0, I_D = 250 \mu A$	100			V	
Gate-Source Threshold Voltage	VGS(th)	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	1		3	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 10 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V			1		
Zero Gate Voltage Drain Current		V _{DS} = 80 V, V _{GS} = 0 V, T _J = 55 °C			10	0 μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	55			Α	
Davis Course Co Clate Basistana	Page	V _{GS} = 10 V, I _D = 15 A		6	7.5		
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 4.5 V, I _D = 10 A		10.5	15.9	mΩ	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 5 V,I _D = 15 A		65		S	
Dynamic ^b							
Input Capacitance	C _{iss}			2670		pF	
Output Capacitance	C _{oss}	$V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		657			
Reverse Transfer Capacitance	C _{rss}			11			
Total Gate Charge ^c	Q_g			48			
Gate-Source Charge ^c	Q _{gs}	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 10 \text{ A}$		5.7		nC	
Gate-Drain Charge ^c	Q _{gd}			7.1		1	
Gate Resistance	ate Resistance R _q f = 1 MHz			1.3		Ω	
Turn-On Delay Time ^c	t _{d(on)}			19			
Rise Time ^c	t _r	$V_{DD} = 50 \text{ V}, I_{D} = 10 \text{ A},$		20			
Turn-Off DelayTime ^c	t _{d(off)}	$R_g = 1 \Omega$, $V_{GS} = 10 V$		33		ns	
Fall Time ^c	t _f			16			
Drain-Source Body Diode Characterist				1			
Continous Source-Drain Diode Current	I _S	T _C = 25 °C			55	A	
Pulse Diode Forward Current	I _{SM}				200		
Body Diode Voltage ^a	V_{SD}	I _S = 1 A			1	V	
Body Diode Reverse Recovery Time	t _{rr}	I _F = 10 A, dl/dt = 100 A/μs, T _I = 25 °C		56		ns	
Body Diode Reverse Recovery Charge	Q_{rr}	o., and = 100 / vpo, 1j = 20 0		38		nC	

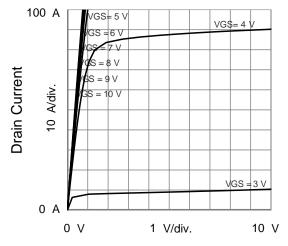
Notes:

- a. Pulse test; pulse width 300 µs, duty cycle 2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

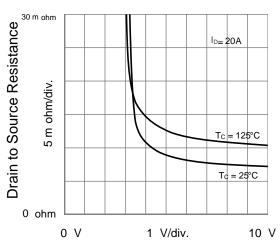
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



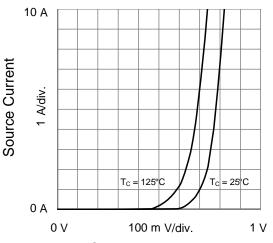
TYPICAL CHARAC TERISTICS (25 °C, unless otherwise noted)



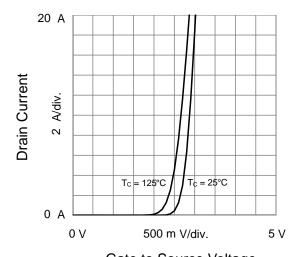
Drain to Source Voltage Output Characteristics



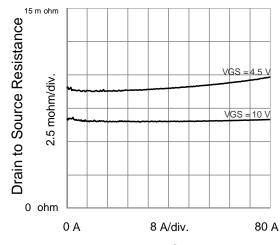
Gate to Source Voltage
Drain to Source Resistance vs. Gate to Source Voltag



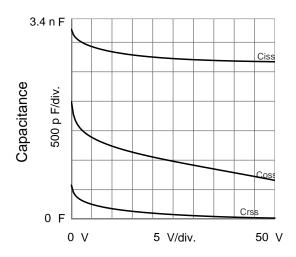
Source to Drain Voltage
Body Diode Forward Characteristics



Gate to Source Voltage Transfer Characteristics



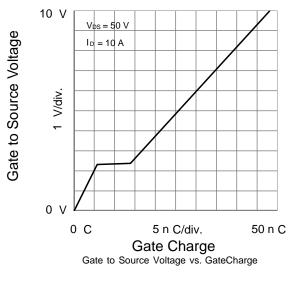
Drain Current

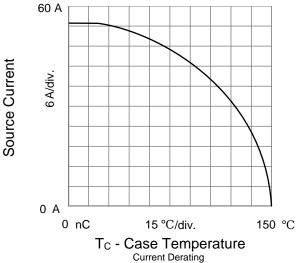


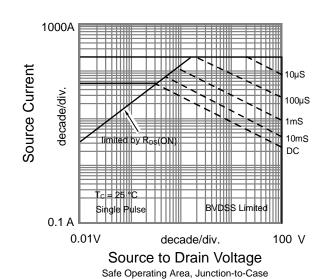
Drain to Source Voltage Capacitances

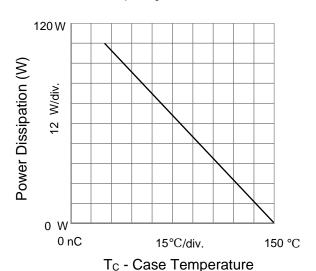


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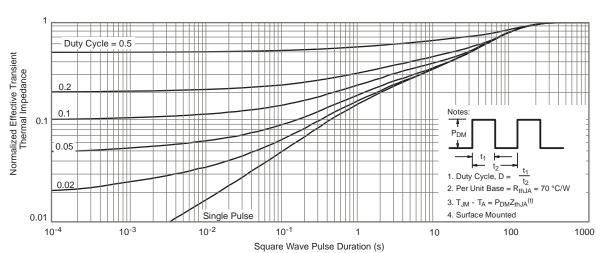








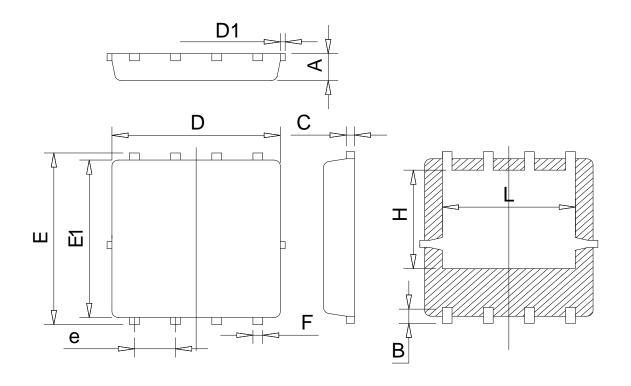
Current Derating



Normalized Thermal Transient Impedance, Junction-to-Ambient



DFN 5X6-8L PACKAGE OUTLINE



COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)

Unit: mm

Symbol	Min	Тур	Max
Α	0.78	0.95	1.12
В	0.45	0.58	0.78
С	0.18	0.254	0.36
D	4.70	5.20	5.45
D1			0.18
Е	5.85	6.05	6.25
E1	5.38	5.55	5.98
е	1.15	1.27	1.40
F	0.18	0.30	0.52
Н	3.25	3.47	3.70
L	3.75	4.00	4.25

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